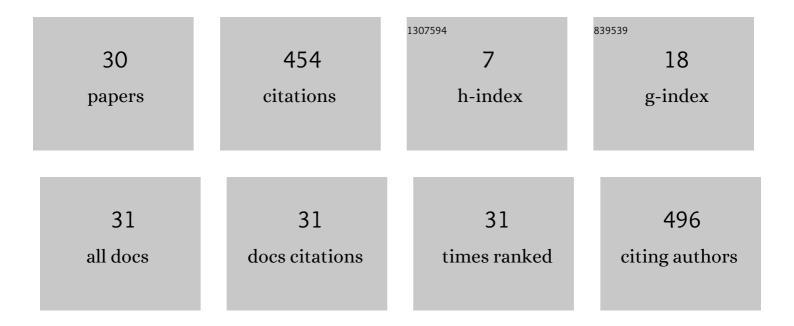
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List of Publications by Year in descending order

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#	Article	IF	CITATIONS
1	Novel Test Fixture for Characterizing MEMS Switch Microcontact Reliability and Performance. Sensors, 2019, 19, 579.	3.8	6
2	Critical Experiments Leading to a Novel Test Fixture Assembly for Microcontact Reliability and Performance Research. , 2019, , .		1
3	Carbon Monoxide Sensing Technologies for Next-Generation Cyber-Physical Systems. Sensors, 2018, 18, 3443.	3.8	68
4	Improving Gold/Gold Microcontact Performance and Reliability Under Low-Frequency AC Through Circuit Loading. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2017, 7, 345-353.	2.5	10
5	Observation and Understanding of the Initial Unstable Electrical Contact Behaviors. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2017, 7, 1272-1279.	2.5	2
6	Improved Sensitivity MEMS Cantilever Sensor for Terahertz Photoacoustic Spectroscopy. Sensors, 2016, 16, 251.	3.8	18
7	Standardized testing of non-standard photovoltaic pavement surfaces. , 2016, , .		5
8	Engineered surfaces to control secondary electron emission for multipactor suppression. , 2016, , .		2
9	Enhancing the thermal performance of temporary fabric structures for the advanced energy efficient shelter system. , 2016, , .		Ο
10	Improved grayscale lithography. , 2016, , .		0
11	Germanium Telluride (GeTe) phase change resistors for reconfigurable circuit applications. , 2015, , .		1
12	Mechanical logic using MEMS. , 2015, , .		0
13	Tunable pressure sensing applications of a MEMS buckled membrane. , 2015, , .		Ο
14	Designing, fabricating and testing multi-junction silicon solar cells. , 2015, , .		0
15	Micro-contact performance and reliability under low frequency, low amplitude, alternating current (AC) test conditions. , 2015, , .		1
16	Investigation of the Surface Adhesion Phenomena and Mechanism of Gold-Plated Contacts at Superlow Making/Breaking Speed. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2015, 5, 771-778.	2.5	8
17	Using Cross-Linked SU-8 to Flip-Chip Bond, Assemble, and Package MEMS Devices. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2015, 5, 301-306.	2.5	4
18	Terahertz Photoacoustic Spectroscopy Using an MEMS Cantilever Sensor. Journal of Microelectromechanical Systems, 2015, 24, 216-223.	2.5	13

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#	Article	IF	CITATIONS
19	Thermal Tuning of MEMS Buckled Membrane Actuator Stiffness. Procedia Engineering, 2014, 87, 1382-1385.	1.2	3
20	A New Look at Azimuthal Wave Propagation Constants of an n-Layered Dielectric Coated PEC Cylinder. IEEE Transactions on Antennas and Propagation, 2013, 61, 2727-2734.	5.1	1
21	A review of micro-contact physics for microelectromechanical systems (MEMS) metal contact switches. Journal of Micromechanics and Microengineering, 2013, 23, 103001.	2.6	104
22	An efficient cost function for the optimization of an <i>n</i> -layered isotropic cloaked cylinder. Journal Physics D: Applied Physics, 2013, 46, 335101.	2.8	2
23	A micro-cantilever based photoacoustic detector of Terahertz radiation for chemical sensing. , 2013, , \cdot		1
24	A Very Robust AlGaN/GaN HEMT Technology to High Forward Gate Bias and Current. Active and Passive Electronic Components, 2012, 2012, 1-4.	0.3	4
25	Using Inductance as a Tuning Parameter for RF Meta-atoms. Nano-Micro Letters, 2012, 4, 103-109.	27.0	2
26	Electrostatically Tunable Meta-Atoms Integrated With In Situ Fabricated MEMS Cantilever Beam Arrays. Journal of Microelectromechanical Systems, 2011, 20, 1366-1371.	2.5	6
27	Reliability testing of AlGaN/GaN HEMTs under multiple stressors. , 2011, , .		11
28	Micromechanical Structure With Stable Linear Positive And Negative Stiffness. Conference Proceedings of the Society for Experimental Mechanics, 2011, , 137-143.	0.5	3
29	Characterization of metal and metal alloy films as contact materials in MEMS switches. Journal of Micromechanics and Microengineering, 2006, 16, 557-563.	2.6	81
30	Selecting metal alloy electric contact materials for MEMS switches. Journal of Micromechanics and Microengineering, 2004, 14, 1157-1164.	2.6	97